In the Specification

Please replace the paragraph spanning page 3, line 11, through page 4, line 3 with the following paragraph:

Fig. 1 illustrates the conventional pattern recognition method 10 currently performed by today's pattern recognition or pattern inspection tools. The method 10 begins when a user places a wafer or other object to be inspected into the inspection apparatus (step 12). After scanning the wafer, the apparatus displays a "field of view" containing images from a portion of the scanned wafer (step 14). ~~Theses~~ These images are to be inspected by the apparatus and thus, are referred to herein as the "inspected images." The apparatus then displays a single pattern box within the field of view (step 16). This pattern box will be used by an operator of the apparatus to select a desired image from the inspected image. The selection is made by placing the pattern box over an image currently displayed in the field of view (step 18). The apparatus "learns" the pattern of the selected image and subsequently uses the learned pattern in a pattern recognition analysis to determine if the wafer has any defects (step 20). The use of "learns" or "learned" herein refers to the process of obtaining pattern information for the selected image and storing the information for subsequent use in a pattern recognition or critical dimension (CD) analysis. The process of learning a pattern and performing a pattern recognition analysis is well known and can be carried out in any known manner.